

# 300 mA High Performance Low-Dropout Linear Regulator

#### **Features**

- Input voltage range: 1.4V to 5.5V
- Fixed outputs of 1.1V, 1.2V, 1.5V, 1.8V, 2.5V, 2.8V, 2.85V, 3.0V, 3.1V, 3.3V
- Rated output current: 300mA
- Quiescent current: typical 50μA
- Typical 0.1μA shutdown current
- Typical 310mV dropout voltage (Iout=300mA, 1.8V output)
- Power supply rejection ratio: typical 90dB (Iout=30mA, freq=1kHz, 1.8V output)
- Noise: typical 33μVrms (I<sub>OUT</sub>=30mA, BW=10Hz to 100kHz, 1.8V output)
- Built-in output short protection: typical 120mA when output short to ground
- DFN 1mmX1mmX0.37mm-4L package and SOT 23-5L package

# **Applications**

Battery-powered equipment
Smart phone
Digital camera
STB

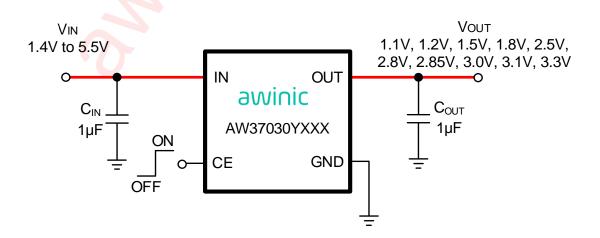
## **General Description**

AW37030YXXX is a low dropout voltage regulator featuring low ON resistance, high PSRR, low Noise, good load/line transient response and smooth soft-start.

AW37030YXXX integrates current limit, short circuit protection, thermal shutdown, sufficiently protecting IC from being damaged.

AW37030YXXX is designed to work with a  $1\mu F$  or more input ceramic capacitor and a  $1\mu F$  or more output ceramic capacitor. The low power dissipation and good dynamic response make AW37030YXXX very suitable for hand-held communication equipment. Tiny package makes high density mounting of the IC on boards possible.

# **Typical Application Circuit**

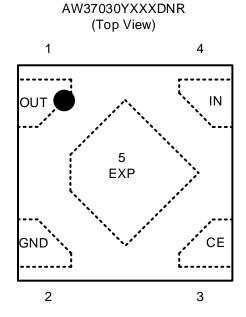


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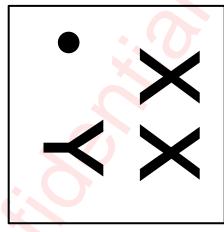


# **Pin Configuration And Top Mark**

DFN 1mmX1mm-4L

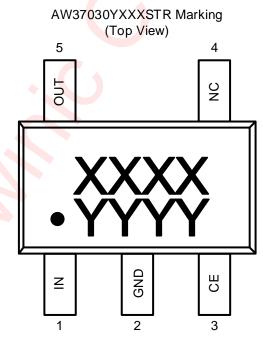


AW37030YXXXDNR Marking (Top View)



XX – AW37030YXXXDNR Y - Production Tracing Code

SOT 23-5L



XXXX - AW37030YXXXSTR YYYY - Production Tracing Code



#### **Pin Definition**

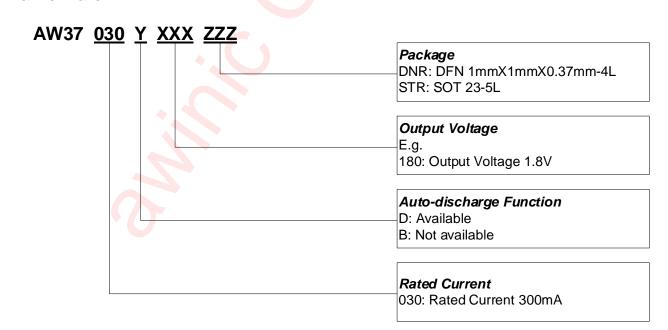
#### DFN 1mmX1mm-4L

No.	NAME	DESCRIPTION
1	OUT	Regulated output voltage pin. Put a $1\mu F$ or more ceramic capacitor at the output pin.
2	GND	Ground.
3	CE	Chip enable pin. Built-in 140nA pull-down current. (High Active)
4	IN	Input supply pin. Put a 1μF or more bypass capacitor at the power supply.
5	EXP	Expose pad should be tied to ground plane for better power dissipation.

#### SOT 23-5L

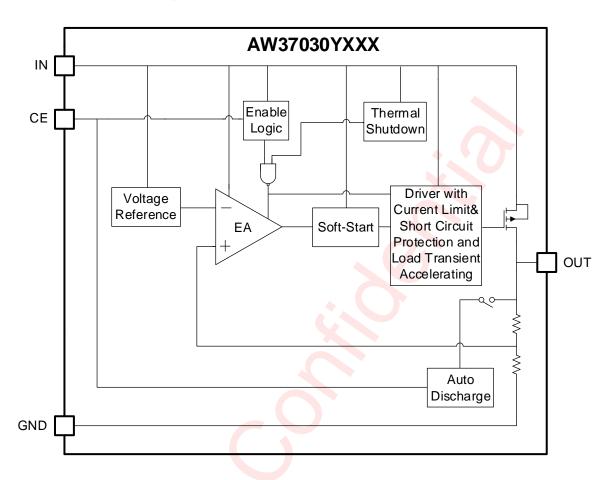
No.	NAME	DESCRIPTION
1	IN	Input supply pin. Put a 1μF or more bypass capacitor at the power supply.
2	GND	Ground.
3	CE	Chip enable pin. Built-in 140nA pull-down current. (High Active)
4	NC	Not connected.
5	OUT	Regulated output voltage pin. Put a $1\mu F$ or more ceramic capacitor at the output pin.

## **Name Rule**

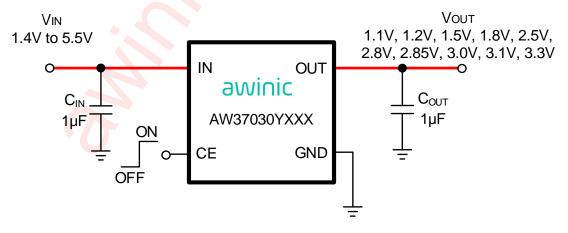




## **Functional Block Diagram**



# **Typical Application Circuits**



**AW37030YXXX Application Circuit** 

#### Notice for typical application circuits:

Capacitance of  $C_{\text{IN}}$  and  $C_{\text{OUT}}$  should be  $1\mu F$  or more.



# **Ordering Information**

Part Number	Temperature	Package	Marking	Moisture Sensitivity Level	Environmental Information	Delivery Form
AW37030D11 0DNR	-40°C∼85°C	DFN 1mmX1mm -4L	VE	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37030D12 0DNR	-40°C∼85°C	DFN 1mmX1mm -4L	SE	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37030D15 0DNR	-40°C∼85°C	DFN 1mmX1mm -4L	CR	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37030D18 0DNR	-40°C∼85°C	DFN 1mmX1mm -4L	HL	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37030D25 0DNR	-40°C∼85°C	DFN 1mmX1mm -4L	J4	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37030D28 0DNR	-40°C∼85°C	DFN 1mmX1mm -4L	ZJ	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37030D28 5DNR	-40°C∼85°C	DFN 1mmX1mm -4L	2V	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37030D30 0DNR	-40°C∼85°C	DFN 1mmX1mm -4L	VA	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37030D31 0DNR	-40°C∼85°C	DFN 1mmX1mm -4L	RJ	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37030D33 0DNR	-40°C∼85°C	DFN 1mmX1mm -4L	PP	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW37030D11 0STR	-40°C∼85°C	SOT 23-5L	75PY	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37030D12 0STR	-40°C∼85°C	SOT 23-5L	VGML	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37030D15 0STR	-40°C∼85°C	SOT 23-5L	ZUM4	MSL3	ROHS+HF	3000 units/ Tape and Reel



# **Ordering Information (Continued)**

Part Number	Temperature	Package	Marking	Moisture Sensitivity Level	Environmental Information	Delivery Form
AW37030D18 0STR	-40°C∼85°C	SOT 23-5L	5HGC	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37030D25 0STR	-40°C∼85°C	SOT 23-5L	K2FA	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37030D28 0STR	-40°C∼85°C	SOT 23-5L	JGLU	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37030D28 5STR	-40°C∼85°C	SOT 23-5L	TKRW	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37030D30 0STR	-40°C∼85°C	SOT 23-5L	N02F	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37030D31 0STR	-40°C∼85°C	SOT 23-5L	2JSX	MSL3	ROHS+HF	3000 units/ Tape and Reel
AW37030D33 0STR	-40°C∼85°C	SOT 23-5L	BB3G	MSL3	ROHS+HF	3000 units/ Tape and Reel



# **Absolute Maximum Ratings**(NOTE1)

PARAMET	RANGE					
Input voltage r	Input voltage range					
Enable control volta	Enable control voltage range					
Output voltage	range	-0.3V to VIN+0.3V, max. 6.5V				
Maximum operating junction	temperature T <sub>JMAX</sub>	150°C				
Recommended operating juncti	on temperature T <sub>JREC</sub>	-40°C to 125°C				
Operating free-air temp	erature range	-40°C to 85°C				
Storage temperat	Storage temperature T <sub>STG</sub>					
Lead temperature (solder	Lead temperature (soldering 10 seconds)					
Junction-to-ambient thermal	DFN 1mmX1mm-4L	228.6°C/W				
resistance θ <sub>JA</sub> <sup>(NOTE2)</sup>	SOT 23-5L	179.3°C/W				
NAi	DFN 1mmX1mm-4L	550mW				
Maximum power consumption	SOT 23-5L	700mW				
	ESD					
HBM (Human body m	nodel) <sup>(NOTE3)</sup>	±2kV				
CDM(Charged device	CDM(Charged device model) (NOTE4)					
	Latch-Up					
Lata La (NO)	TES)	+IT: 200mA				
Latch-Up <sup>(NOT</sup>		- IT: -200mA				

NOTE1: Conditions out of those ranges listed in "absolute maximum ratings" may cause permanent damages to the device. In spite of the limits above, functional operation conditions of the device should within the ranges listed in "recommended operating conditions". Exposure to absolute-maximum-rated conditions for prolonged periods may affect device reliability.

NOTE2: Thermal resistance from junction to ambient follows JEDEC 2S2P standards, and is highly dependent on PCB layout.

NOTE3: All pins. Test Condition: ESDA/JEDEC JS-001-2018.

NOTE4: All pins. Test Condition: ESDA/JEDEC JS-002-2018.

NOTE5: Test Condition: JESD78E.



## **Electrical Characteristics**

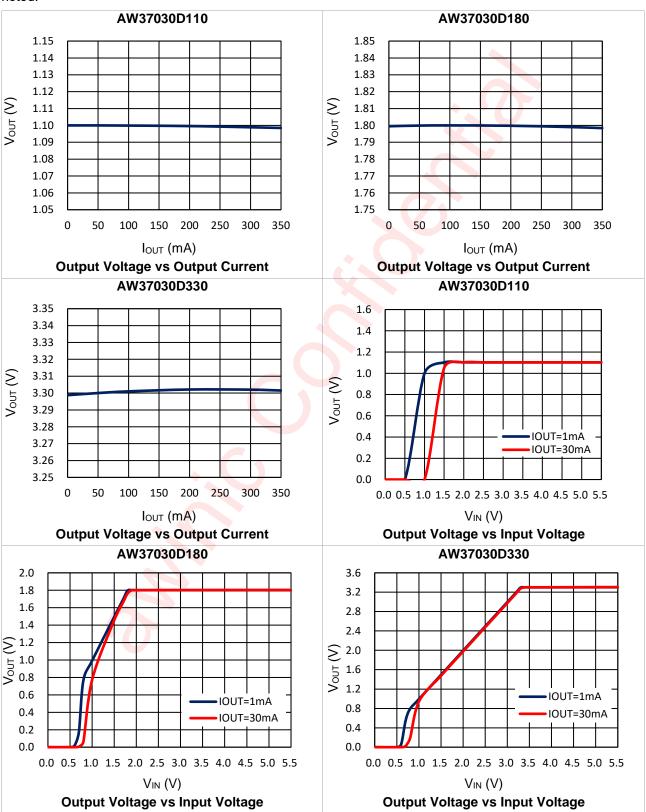
 $V_{IN}=V_{OUT(SET)}+1V$ ,  $V_{CE}>1V$ ,  $I_{OUT}=1mA$ ,  $C_{IN}=C_{OUT}=1\mu F$ ,  $T_A=25^{\circ}C$  (unless otherwise noted)

PA	RAMETER	TEST C	MIN	TYP	MAX	UNIT		
Vin	Input Voltage Range			1.4		5.5	V	
Vous coo	Output Voltage	T <sub>A</sub> =	T <sub>A</sub> =25°C			1	%	
Vout_acc	Accuracy	-40°C ≤	-2		2	%		
LOAD <sub>Reg</sub>	Load Regulation	1mA≤l <sub>O</sub> ı	וד≤300mA		1	20	mV	
LINE <sub>Reg</sub>	Line Regulation	V <sub>OUT(SET)</sub> +0.	5V≤V <sub>IN</sub> ≤5.5V		1	5	mV	
			V <sub>OUT(SET)</sub> =1.1V		680			
			V <sub>OUT(SET)</sub> =1.2V		576			
		I <sub>OUT</sub> =300mA, When V <sub>OUT</sub>	V <sub>OUT(SET)</sub> =1.8V		310			
V <sub>dropout</sub>	Dropout Voltage	falls 100mV	V <sub>OUT(SET)</sub> =2.5V		203		mV	
		below Vout(SET)	V <sub>OUT(SET)</sub> =2.8V		184			
			V <sub>OUT(SET)</sub> =3.0V		175			
			V <sub>OUT(SET)</sub> =3.3V		158			
I <sub>SD</sub>	Shutdown Current	V <sub>CE</sub> <0.4V			0.1	1	μΑ	
lα	Quiescent Current	l <sub>ouт</sub> =0mA			50	100	μΑ	
Vceh	CE Input Voltage "H"	-40°C ≤T <sub>A</sub> ≤85°C		1			V	
VCEL	CE Input Voltage "L"	-40°C ≤	-40°C ≤T <sub>A</sub> ≤85°C			0.4	V	
PSRR	Power Supply Ripple Rejection		nA, f=1kHz <sub>ET)</sub> =1.8V		90		dB	
	*	I <sub>OUT</sub> =30mA	V <sub>OUT(SET)</sub> =1.1V		21			
V <sub>N</sub>	Output Voltage Noise	BW=10Hz to	V <sub>OUT(SET)</sub> =1.8V		33		μVrms	
		100kHz	V <sub>OUT(SET)</sub> =3.3V		46			
Icl	Output Current Limit	V <sub>OUT</sub> =90 <sup>o</sup>	%*Vout(set)	300			mA	
Isc	Short Current Limit	V <sub>OUT</sub> <10 <sup>o</sup>	%*V <sub>OUT(SET)</sub>		120		mA	
VTC	Output Voltage Temperature Coefficient	-40°C ≤	⊊T <sub>A</sub> ≤85°C		±40		ppm/° C	
Roisc	R <sub>DISC</sub> Auto Discharge Resistance		V <sub>IN</sub> =4V, V <sub>CE</sub> <0.4V, V <sub>OUT</sub> =2.8V		130		Ω	
Ice	CE Pull Down Current				140		nA	
T <sub>SDH</sub>	Thermal Shutdown Threshold	Tempera	ture Rising		160		°C	
T <sub>SDL</sub>	Thermal Shutdown Reset Threshold	Tempera	Temperature Falling		130		°C	



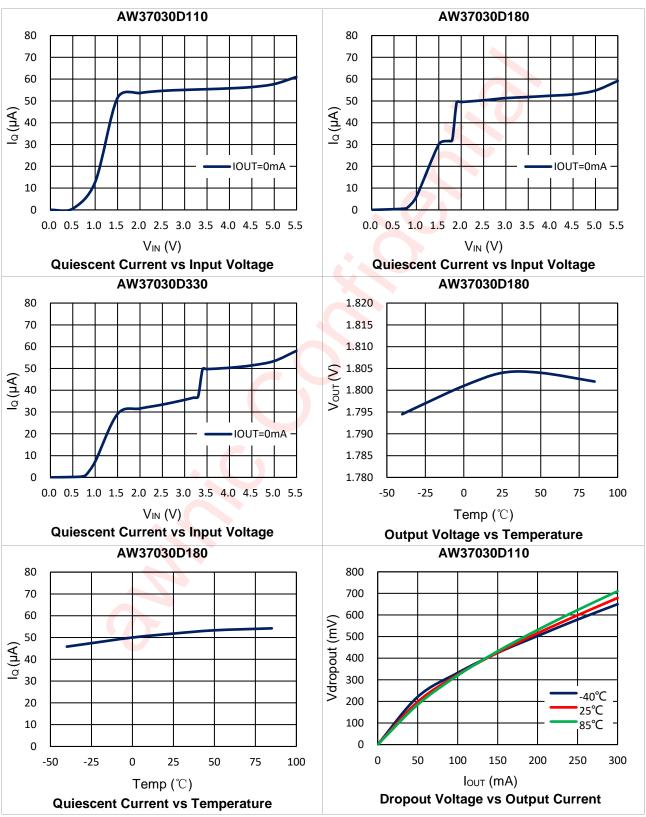
## **Typical Characteristics**

 $V_{\text{IN}}=V_{\text{OUT}(\text{SET})}+1V$ ,  $V_{\text{CE}}>1V$ ,  $I_{\text{OUT}}=1\text{mA}$ ,  $C_{\text{IN}}=C_{\text{OUT}}=1\mu\text{F}$ ,  $T_{\text{A}}=25^{\circ}\text{C}$ , In Typical Application Circuit, unless otherwise noted.



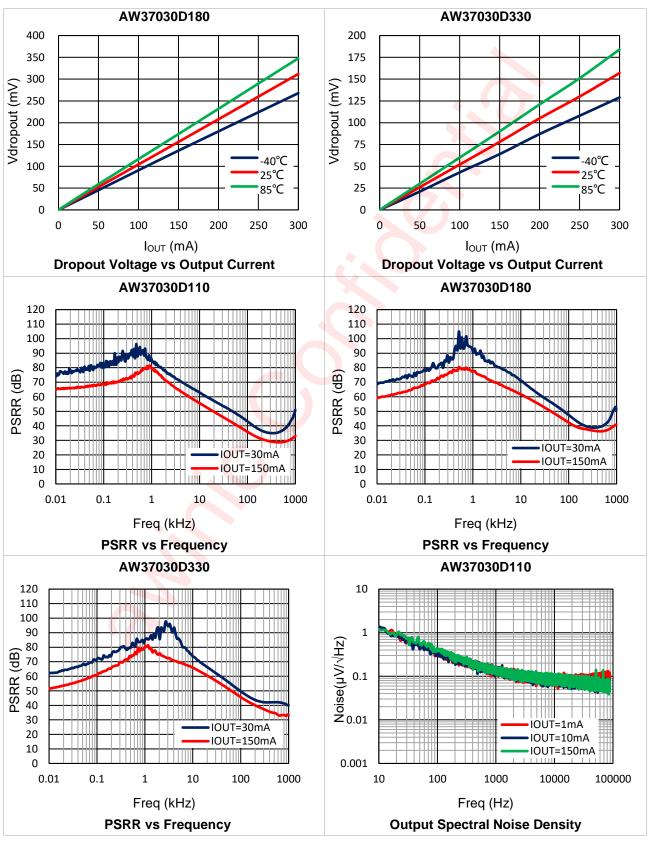


 $V_{\text{IN}}=V_{\text{OUT}(\text{SET})}+1V$ ,  $V_{\text{CE}}>1V$ ,  $I_{\text{OUT}}=1\text{mA}$ ,  $C_{\text{IN}}=C_{\text{OUT}}=1\mu\text{F}$ ,  $T_{\text{A}}=25^{\circ}\text{C}$ , In Typical Application Circuit, unless otherwise noted.

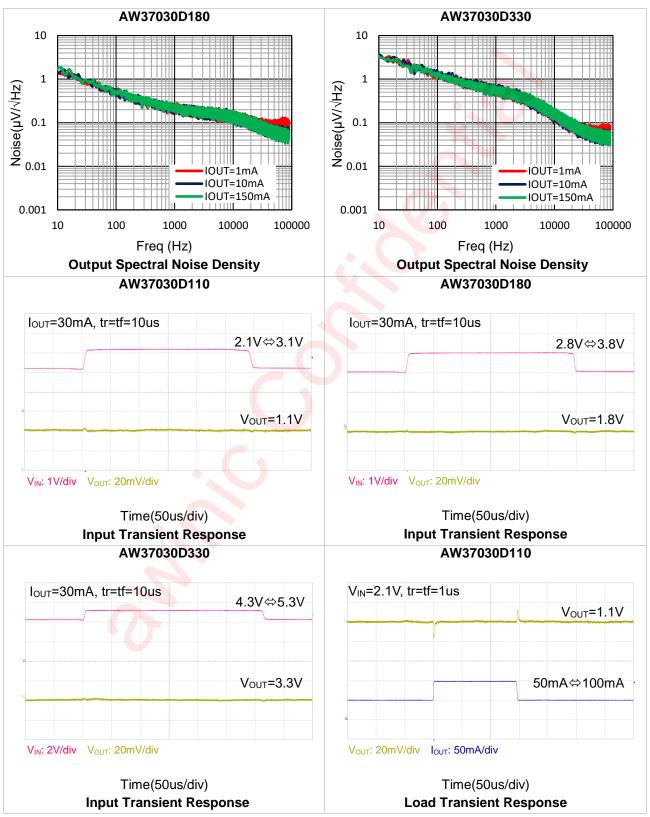




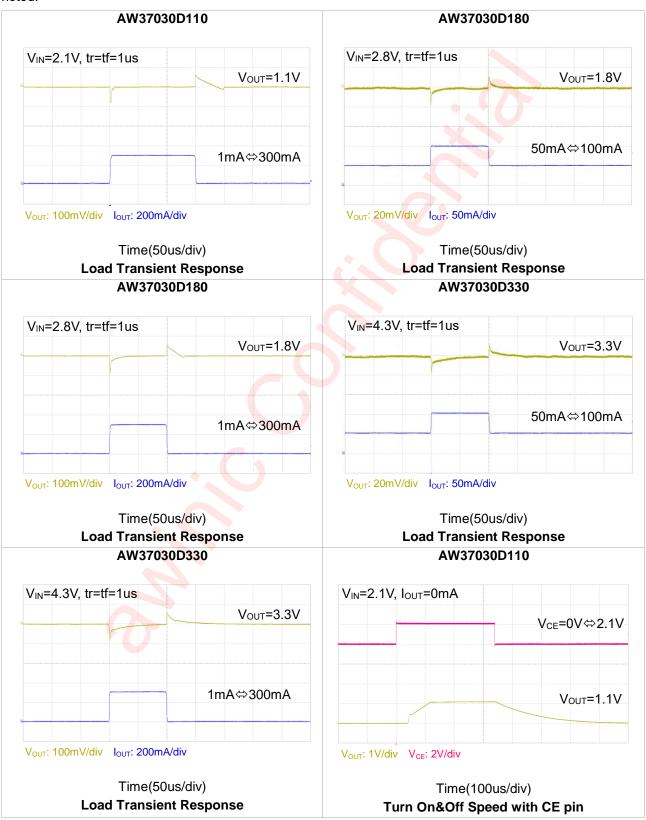
 $V_{\text{IN}}=V_{\text{OUT}(\text{SET})}+1V$ ,  $V_{\text{CE}}>1V$ ,  $I_{\text{OUT}}=1\text{mA}$ ,  $C_{\text{IN}}=C_{\text{OUT}}=1\mu\text{F}$ ,  $T_{\text{A}}=25^{\circ}\text{C}$ , In Typical Application Circuit, unless otherwise noted.



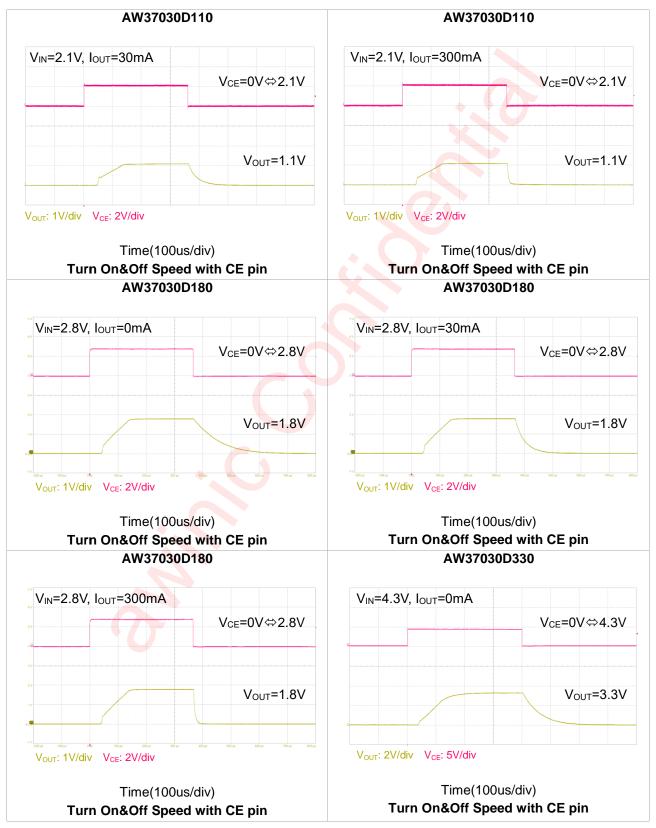




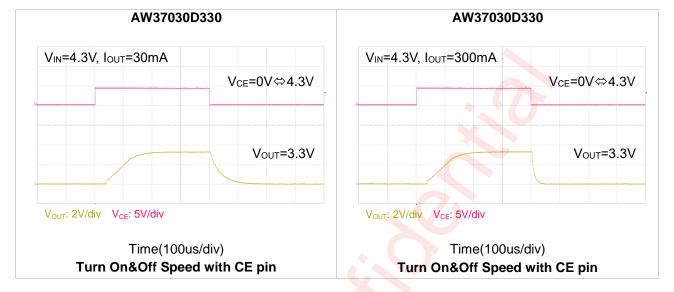














Jul. 2021 V1.6

## **Detailed Functional Description**

AW37030YXXX is a low dropout voltage regulator. After powered on, with CE pin assertion, feedback voltage signal from the integrated resistor network and a voltage related to the voltage reference are transmit to positive input terminal and negative input terminal of an error amplifier (EA) respectively. The output signal of EA is used to control the open-state of power MOSFET. After soft-start, feedback voltage signal compares with the established reference voltage, making output voltage stable and accurate. AW37030YXXX integrates function of load transient accelerating, making LDO obtain excellent dynamic load transient response performance.

#### **Enable Operation**

AW37030YXXX uses CE pin to realize enable operation. Applying proper value of voltage to CE pin can make IC enable/disable.

If the voltage of CE pin is less than 0.4V, AW37030YXXX is guaranteed to be disabled. In this state, function modules of IC and power MOSFET are turned off. And the auto discharge function is enabled making output discharge through a on-state NMOSFET to Ground. In disable state, AW37030YXXX only consumes a typical 10nA current.

If the voltage of CE pin is more than 1V, AW37030YXXX is guaranteed to be enabled. In this state, the auto discharge function is disabled, and AW37030YXXX regulates output voltage to the designed value of voltage.

A 140nA pull down current to Ground is built-in at CE pin, making sure that the IC is disabled when CE pin floats. If Enable function is not required, CE pin should be connected directly to IN pin.

#### **Output Current Limit**

AW37030YXXX integrates output current limit function, protecting IC from excessive current.

When the load is excessively heavy, AW37030YXXX limits the current flowing through the IC to a typical 500mA current. This value is specially designed, so that IC is protected properly and the output capability of 300mA is not influenced either.

Meanwhile, AW37030YXXX integrates a 120mA fold-back current limit function, lowering the system dissipation when output overload or short to Ground.

#### Thermal Shutdown

AW37030YXXX integrates thermal shutdown function, protect IC from excessively high temperature.

When the chip temperature exceeds 160°C, AW37030YXXX detects it as an over-temperature event, triggering thermal shutdown, which will turn off the main function module, including power MOSFET. This inhibits increase of chip's temperature. IC would keep the protection-state on until the chip's temperature falls below to 130°C. At this moment, the over-temperature protection-state is released, IC resumes to work again. The hysteresis avoids IC's turning off and on frequently around the the Thermal Shutdown threshold.

#### **Auto Discharge**

AW37030YXXX makes output voltage discharge quickly when in CE disable state or thermal shutdown state, benefit from integrating auto discharge function. Auto discharge function is implemented by integrated a NMOSFET of typical  $130\Omega$  Rdson route from Output to Ground, and the route is get through in CE disable state or thermal shutdown state. This feature prevents residual charge voltage on the output capacitor, which may impact proper power up of the system connected to the converter. It should be noted that auto discharge function is optional according to different specs.



## **Application Information**

#### **Capacitors Selection**

IN pin: Input Capacitor CIN

AW37030YXXX advises to use a  $1\mu F$  or more X5R or X7R ceramic capacitor at IN pin as shown in Typical Application Circuit.

#### **OUT pin: Output Capacitor Cout**

AW37030YXXX advises to use a  $1\mu F$  or more X5R or X7R ceramic capacitor at OUT pin as shown in Typical Application Circuit.

### **Recommended Components List**

Component	PART No.	DESCRIPTION	MFR	TYP.	UNIT
Cin	GRM155R61A105KE15	10V, X5R, 0402	MURATA	1	μF
Соит	GRM155R61A105KE15	10V, X5R, 04 <mark>0</mark> 2	MURATA	1	μF

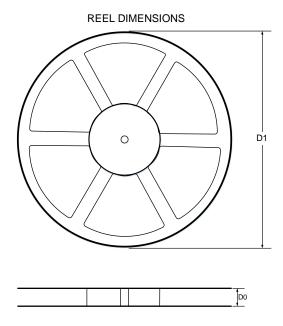
## **PCB Layout Consideration**

The performance of a power source circuit using this device is highly dependent on a peripheral circuit. To obtain the optimal performance, a peripheral component or the device mounted on PCB should not exceed its rated voltage, rated current or rated power. When designing a peripheral circuit, guidelines below for PCB layout of AW37030YXXX should be obeyed:

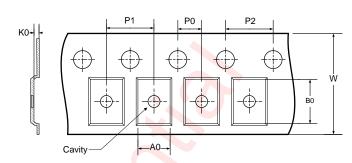
- 1. All peripheral components should be placed as close to the chip as possible. C<sub>IN</sub> and C<sub>OUT</sub> should be close to IN and OUT pins respectively. Avoid connecting device and chip pins with two different layers of copper, use the same layer of copper instead.
- 2. IN and OUT pin are the large current input and output of the chip, make IN, OUT, and meanwhile GND lines sufficient.
- 3. The connection lines between the planes of C<sub>IN</sub> or C<sub>OUT</sub> and respective chip pin should be as short and wide as possible, to reduce noise and EMI interference, or it may cause noise pickup or unstable operation.
- 4. The exposed plane of chip and GND pins must be connected to the large-area ground layer of PCB directly, meanwhile place sufficient vias below the exposed plane. Thus we can decrease the thermal resistor on the board to optimize heat-diffusion performance.

# **Tape And Reel Information**

DFN 1mmX1mm-4L

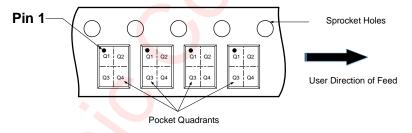


#### TAPE DIMENSIONS



- A0: Dimension designed to accommodate the component width
- B0: Dimension designed to accommodate the component length
- K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P0: Pitch between successive cavity centers and sprocket hole
- P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
- D1: Reel Diameter
- D0: Reel Width

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



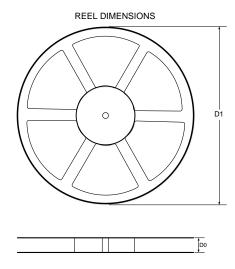
#### **DIMENSIONS AND PIN1 ORIENTATION**

ſ	D1	D0	A0	B0	K0	P0	P1	P2	W	Pin1 Quadrant
	(mm)	Fiiii Quadiani								
1	178	8.4	1.14	1.17	0.56	2	4	4	8	Q1

All dimensions are nominal



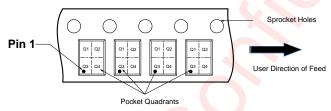
#### SOT 23-5L



# TAPE DIMENSIONS K0-

- A0: Dimension designed to accommodate the component width B0: Dimension designed to accommodate the component length K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P0: Pitch between successive cavity centers and sprocket hole
- P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
- D1: Reel Diameter D0: Reel Width

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### DIMENSIONS AND PINT ORIENTATION

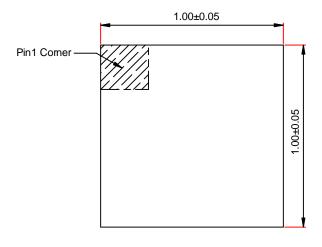
DiiviLivo	SIME NO INTERNATION									
D1	D0	A0	B0	K0	P0	P1	P2	W	Pin1 Quadrant	
(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	Pini Quadrant	
178	8.4	3.3	3.2	1.4	2	4	4	8	Q3	

All dimensions are nominal

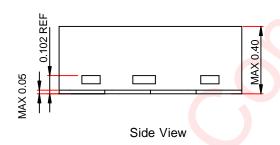


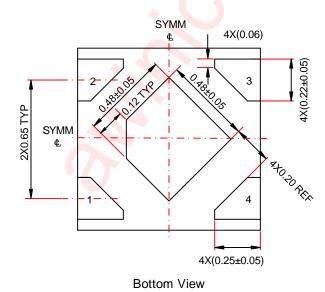
# **Package Description**

DFN 1mmX1mm-4L



Top View





0.102 REF

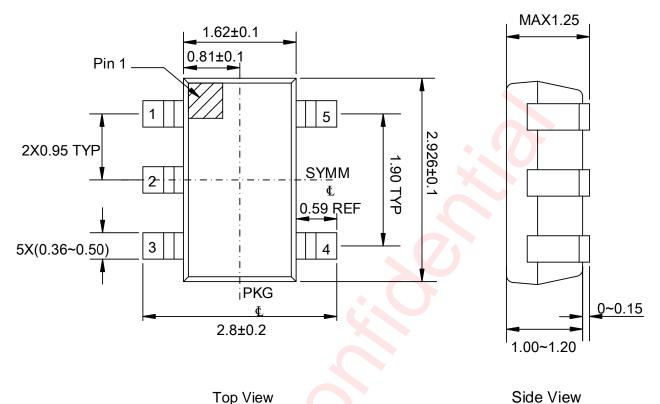
MAX 0.40

MAX 0.05

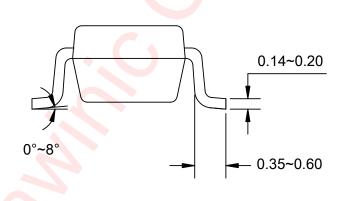
Side View

Unit:mm

SOT 23-5L







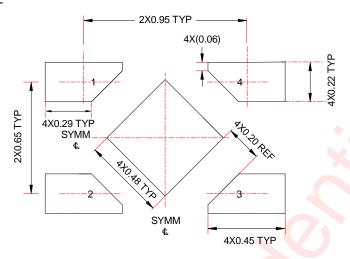
Side View

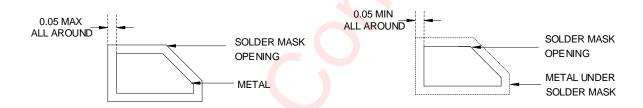
Unit: mm



#### **Land Pattern Data**

DFN 1mmX1mm-4L





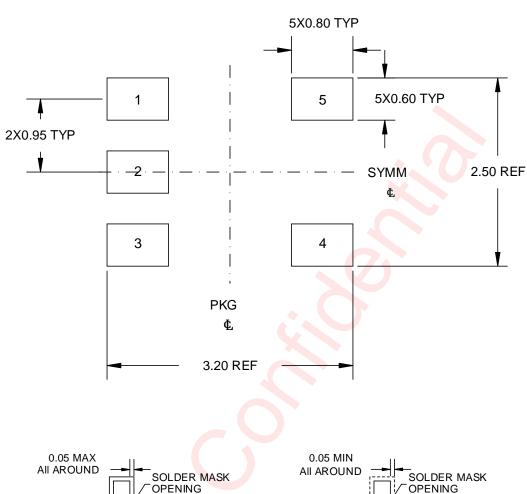
NON SOLDER MASK DEFINED

SOLDER MASK DEFINED

UNIT: mm

22

SOT 23-5L



SOLDER MASK DEFINED

METAL UNDER SOLDER MASK

**METAL** 

NON SOLDER MASK DEFINED



# **Revision History**

Version	Date	Change Record
V1.0	Jan. 2020	Officially released
V1.1	Nov. 2020	V <sub>OUT_ACC</sub> at T <sub>A</sub> =25 °C change to $\pm$ 1%; LOAD <sub>REG</sub> MAX change to 20mV; I <sub>Q</sub> MAX change to 100μA
V1.2	Jan. 2021	Add V <sub>OUT</sub> of 1.2V and 2.5V
V1.3	Jan. 2021	Add Maximum power consumption and Inrush Current
V1.4	Mar. 2021	Add test waves of 1.2V; Add name rule; Add VouT of 1.1V and 1.5V; Add wave of Output Spectral Noise Density
V1.5	Apr. 2021	Add SOT 23-5L package
V1.6	Jul. 2021	Add V <sub>OUT</sub> of 2.85V and 3.1V; Remove test waves of 1.2V and add electical characteristics of 1.1V



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